



Material Content Data Sheet



Sales Product Name	SAF-XE164H-96F66L AC			Issued		29. August 2013		
MA#	MA001060010							
Package	PG-LQFP-100-3			Weight*		752.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	40.856	5.43	5.43	54289	54289
leadframe	inorganic material	phosphorus	7723-14-0	0.068	0.01		90	
	non noble metal	zinc	7440-66-6	0.272	0.04		361	
	non noble metal	iron	7439-89-6	5.439	0.72		7228	
	non noble metal	copper	7440-50-8	220.854	29.35	30.12	293472	301151
wire	noble metal	gold	7440-57-5	4.149	0.55	0.55	5514	5514
encapsulation	organic material	carbon black	1333-86-4	2.299	0.31		3055	
	plastics	epoxy resin	-	62.082	8.25		82495	
	inorganic material	silicondioxide	60676-86-0	395.485	52.54	61.10	525522	611072
leadfinish	non noble metal	tin	7440-31-5	8.316	1.11	1.11	11051	11051
plating	noble metal	silver	7440-22-4	2.259	0.30	0.30	3002	3002
glue	plastics	epoxy resin	-	2.619	0.35		3480	
	noble metal	silver	7440-22-4	7.858	1.04	1.39	10441	13921
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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